



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP 2309m

HP 2309v

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	4 {Backlight Assembly (I type)}
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		27
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1 (C854 location)
External electrical cables and cords		3
Gas Discharge Lamps		4
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1: Bushing Screwdriver	(HEX5.5MM)
Description #2: Crossing Screwdriver	2#
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:













1. Lay the monitor on the desk, remove the VESA mounting cover with hand.
2. Unlock the 4 screws which they fix the VESA mounting by 2# screwdriver.
3. Unlock the 4 screws which they fix the stand by 2# screwdriver.
4. Remove the front bezel with hand from product
5. Remove the backcover with hand from Product.
6. Seperate the Keypad and backcover with hand
7. Unlock the 2 screws which they fix the chassis and panel, and then pull the LVDS out .
8. Unlock 2 screws for DVI port, D-SUB port, Power port, and 7 screws which they fix between chassis and PCA boards, power board and IF board. Pull the wires out.
9. Unlock the 2 screws which they fix between the bottom-side and the base, and then unlock the 12 screws which they fix between the base and base-cover.
10. Remove the arm-rear and then unlock the 4 screws which they fix between the arm-front and the rion.
11. To see the detail process are as attached files including assemble panel.




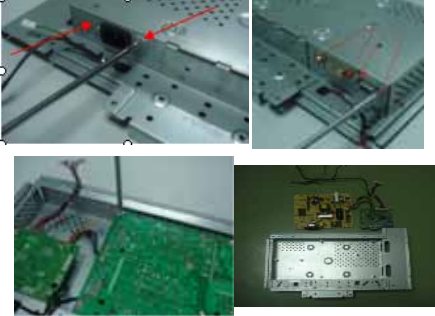

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).







Disassembly Flowchart for HP 2309 Model

Issue Date: Dec. 31, 2008
Initiator: Candy Zheng

Action	Tool	Photo
Lay the Monitor on the desk. 	N/A	
Remove the VESA mounting cover with hand. 	N/A	
Unlock the 4 screws which they fix the VESA mounting by #2 scewdriver. 	#2 Crossing Screw Driver	
Unlock the 4 screws which they fix the stand by 2# screwdriver. 	#2 Crossing Screw Driver	
Remove the front bezel out with hand. 	N/A	
Remove the back cover out with hand. 	N/A	

<p>↓</p> <p>Unlock the 6 screws which fix the speaker grill ,and take the sub-bezel out.</p>	<p>#2 Crossing Screw Driver</p>	
<p>↓</p> <p>Take the keypad out.</p>	<p>N/A</p>	
<p>↓</p> <p>Unlock the 2 screws which fix the chassis and panel, and then pull the LVDS out .</p>	<p>#2 Crossing Screw Driver</p>	
<p>↓</p> <p>Unlock 2 screws for DVI port, D-SUB port, Power port, and 7 screws which they fix between chassis PCA boards, power board and IF board. Pull the wires out.</p>	<p>#2 Crossing Screw Driver and #1 Bushing Screw Driver</p>	
<p>↓</p> <p>Unlock the 2 screws which they fix between the bottom-side and the base, and then unlock the 12 screws which they fix between the base and base-cover.</p> <p>↓</p>	<p>#2 Crossing Screw Driver</p>	

<p style="text-align: center;">↓</p> <p>Remove the arm-rear and then unlock the 4 screws which they fix between the arm-front and the rion.</p> <p style="text-align: center;">↓</p>	<p>#2 Crossing Screw Driver</p>	  
<p>The panel</p>	<p>N/A</p>	

Technical Notification

**- Sequence of Module Disassembly for Lamp Separation -
(LTM230HT01)**

DATE : Oct. 08, 2008

**Application Engineering 1 ,
HD development, LCD Business**

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Sequence of Module Disassembly for Lamp Separation

● LTM230HT01 Module front and rare side



● Disassemble top chassis and PCB cover



Sequence of Module Disassembly for Lamp Separation

- Disassemble the panel from the Mold frame



- Disassemble the mold frame, sheets and diffuser plate from the bottom chassis

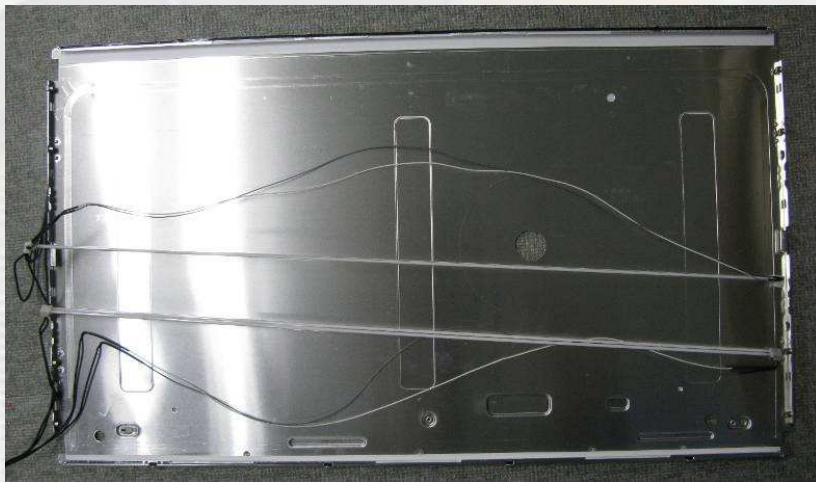


Sequence of Module Disassembly for Lamp Separation

- Separate side mold to pull out lamp



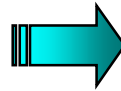
- Separate lamp from backlight



Method of lamp disassembly on LM230WF1-TLA3/TLB3



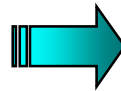
Step 1 : Rear side view



Step 2 : Unfix the screws (3 Points)



Step 3 : Remove the Cover Shield

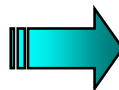


Step 4 : Separate wires from the tape

Method of lamp disassembly on LM230WF1-TLA3/TLB3



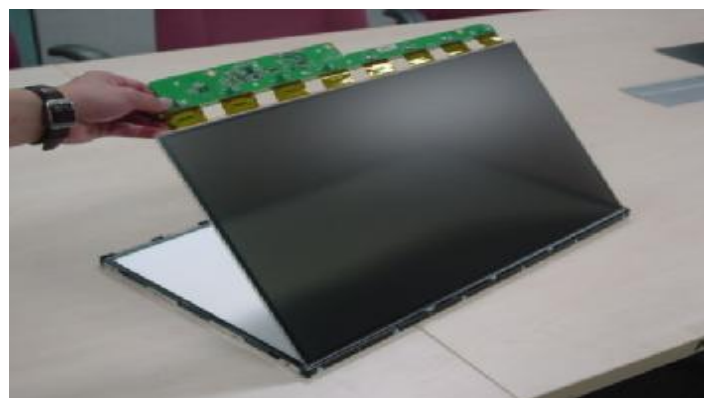
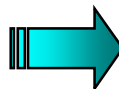
Step5 : Dismantle the case top(Down)



Step6 : Dismantle the case top(left/right)



Step7 : Separate case top(push the case top because of damages on COF)

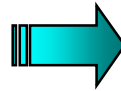


Step8 : Separate Board Assy

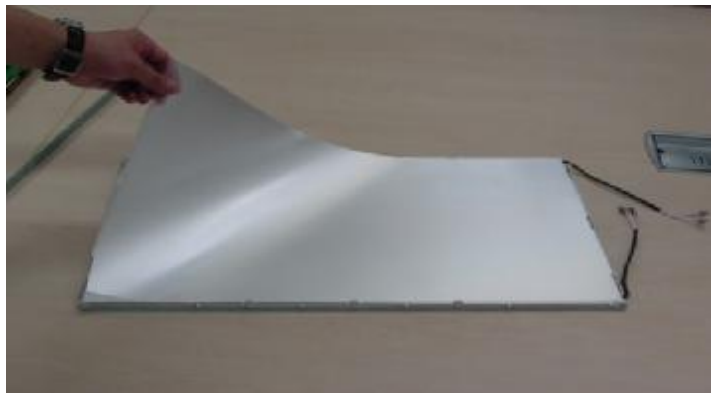
Method of lamp disassembly on LM230WF1-TLA3-731



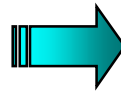
Step9 : Unfix the BL Screw



Step10 : remove S/Main



Step11 : remove the Optical Sheets

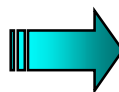


Step12 : remove the LGP

Method of lamp disassembly on LM230WF1-TLA3-731



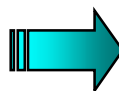
Step13 : remove lamp wire tapes
(left/right)



Step14 : Separate wires from Cover bottom



Step15 : Separate Lamp holder(H) from
holder Guide of Cover bottom



Step16 : Separate Lamp holde(G) from
holder Guide of Cover bottom.

Method of lamp disassembly on LM230WF1-TLA3-731



Final : Lamp Assy